

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
Contact Info: ti.com/support
Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
Created on: 06/08/2022

Details for "TLV2254AQD"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV2254AQD	NIPDAU	Level-1-260C-UNLIM	TI TAIWAN A/T	D 14	3.91X8.65X1.58	193.9

***Total Device Mass**
The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

				Homogeneous Material Level		Component Level	
Component	Substance	CAS Number	Amount (mg)	Percentage %	ppm	Percentage %	ppm
Bond Wire							
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000001	0.000705	7	0.000001	0
Precious Metals	Gold	7440-57-5	0.14176	99.997884	999979	0.073092	731
Precious Metals	Silver	7440-22-4	0.000002	0.001411	14	0.000001	0
Sub-Total			0.141763	100	1000000	0.073094	731
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.343935	69.999959	700000	0.177335	1773
Thermoplastics	Epoxy	85954-11-6	0.147401	30.000041	300000	0.076001	760
Sub-Total			0.491336	100	1000000	0.253335	2533
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	78.9669	97.49	974900	40.715756	407158
Copper and Its Alloys	Iron	7439-89-6	1.944	2.4	24000	1.002337	10023
Copper and Its Alloys	Phosphorus	7723-14-0	0.0243	0.03	300	0.012529	125
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.0081	0.01	100	0.004176	42
Zinc and Its Alloys	Zinc	7440-66-6	0.0567	0.07	700	0.029235	292
Sub-Total			81	100	1000000	41.764034	417640
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	8.27544	95.12	951200	4.266861	42669
Precious Metals	Gold	7440-57-5	0.06786	0.78	7800	0.034989	350
Precious Metals	Palladium	7440-05-3	0.3567	4.1	41000	0.183916	1839
Sub-Total			8.7	100	1000000	4.485767	44858
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	77.200105	76	760000	39.804787	398048
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	3.555268	3.5	35000	1.833115	18331
Other Plastics and Rubber	Carbon Black	1333-86-4	0.304737	0.3	3000	0.157124	1571
Thermoplastics	Epoxy	85954-11-6	20.518975	20.2	202000	10.579693	105797
Sub-Total			101.579085	100	1000000	52.37472	523747
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	2.0346	100	1000000	1.049051	10491
Sub-Total			2.0346	100	1000000	1.049051	10491
Total							
			193.946784			100	1000000

Important Note
The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
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Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to [www.ti.com/ecoinfo](#)
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in [http://www.ti.com/lit/pdf/szzq088](#)

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.